

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

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In re Patent Application of:  
Toshiyuki Nagase et al.

Application No.: 10/599,622

Confirmation No.: 1764

Filed: October 3, 2006

Art Unit: N/A

For: AI/AIN JOINT MATERIAL, BASE PLATE  
FOR POWER MODULE, POWER MODULE,  
AND MANUFACTURING METHOD OF  
AI/AIN JOINT MATERIAL (AS AMENDED)

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Examiner: Not Yet Assigned

**SECOND PRELIMINARY AMENDMENT**

MS Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

**INTRODUCTORY COMMENTS**

Prior to examination on the merits, please amend the above-identified U.S. patent application as follows:

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 3 of this paper.

**Remarks/Arguments** begin on page 8 of this paper.